



MICROCHIP

MGC3030
Woodstar Development Kit
User's Guide

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, flexPWR, JukeBlox, KEELOQ, KEELOQ logo, Kleer, LANCheck, MediaLB, MOST, MOST logo, MPLAB, OptoLyzer, PIC, PICSTART, PIC³² logo, RightTouch, SpyNIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

The Embedded Control Solutions Company and mTouch are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, ECAN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, KleerNet, KleerNet logo, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, RightTouch logo, REAL ICE, SQI, Serial Quad I/O, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2014-2015, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

ISBN: 978-1-63276-971-8

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949 ==

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC[®] MCUs and dsPIC[®] DSCs, KEELOQ[®] code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

Object of Declaration: MGC3030 Woodstar Development Kit User's Guide

EU Declaration of Conformity


This declaration of conformity is issued by the manufacturer.

The development/evaluation tool is designed to be used for research and development in a laboratory environment. This development/evaluation tool is not intended to be a finished appliance, nor is it intended for incorporation into finished appliances that are made commercially available as single functional units to end users. This development/evaluation tool complies with EU EMC Directive 2004/108/EC and as supported by the European Commission's Guide for the EMC Directive 2004/108/EC (8th February 2010).

This development/evaluation tool complies with EU RoHS2 Directive 2011/65/EU.

For information regarding the exclusive, limited warranties applicable to Microchip products, please see Microchip's standard terms and conditions of sale, which are printed on our sales documentation and available at www.microchip.com.

Signed for and on behalf of Microchip Technology Inc. at Chandler, Arizona, USA


Derek Carlson
VP Development Tools

16-July-2013
Date

MGC3030 Woodstar Development Kit User's Guide

NOTES:



MGC3030 WOODSTAR DEVELOPMENT KIT USER'S GUIDE

Table of Contents

Preface	7
Introduction.....	7
Document Layout	7
Conventions Used in this Guide	8
Warranty Registration.....	9
Recommended Reading.....	9
The Microchip Web Site	10
Development Systems Customer Change Notification Service	10
Customer Support	11
Revision History	11
Chapter 1. Overview	
1.1 Introduction	13
1.2 Woodstar Concept and Deliverables	13
1.3 Woodstar Development Kit Package Content	14
1.4 GestIC [®] Hardware References	15
1.5 Aurea Software Package	16
1.6 MGC3030/3130 Software Development Kit (SDK)	16
Chapter 2. Getting Started	
2.1 Prerequisites	17
2.2 Step 1: Development Kit Assembly	17
2.3 Step 2: Connecting the Woodstar Development Kit to the PC	18
2.4 Step 3: Installing Windows [®] CDC Driver	18
2.5 Step 4: Starting Aurea GUI	18
Chapter 3. Woodstar Boards – Hardware Description	
3.1 Overview	21
3.1.1 I ² C [™] to USB Bridge	21
3.1.2 MGC3030 Unit	21
3.1.3 95x60 mm Reference Electrode PCB	21
3.2 The MGC3030 Unit	22
3.3 95x60 mm Reference Electrode	23
3.4 I ² C [™] to USB Bridge	25
Chapter 4. System Integration Using Woodstar	
4.1 Introduction	27
4.2 Integration Examples	27

MGC3030 Woodstar Development Kit User's Guide

Chapter 5. Troubleshooting

5.1 Power LED Does Not Illuminate	31
5.2 LED 1 Blinks Fast	31
5.3 Signal Streaming Stops	31
5.4 Electrode Signals are Zero	31
5.5 LED 1 and 2 on I ² C to USB Bridge are OFF	32

Appendix A. Schematics

A.1 Introduction	33
A.2 Bill of Materials	33
A.3 Board Schematics and Layout	35

Appendix B. Sensitivity Profile and Capacitances

B.1 Introduction	39
B.2 Sensitivity Profiles	39
B.3 Electrode Capacities	40

Appendix C. Driver Installation Manual

C.1 Open Device Manager	41
C.2 Select Device	41
C.3 Locate Driver	42
C.4 Verify Communication	42

Appendix D. Glossary

Worldwide Sales and Service	45
-----------------------------------	----



MGC3030 WOODSTAR DEVELOPMENT KIT USER'S GUIDE

Preface

NOTICE TO CUSTOMERS

All documentation becomes dated, and this manual is no exception. Microchip tools and documentation are constantly evolving to meet customer needs, so some actual dialogs and/or tool descriptions may differ from those in this document. Please refer to our web site (www.microchip.com) to obtain the latest documentation available.

Documents are identified with a "DS" number. This number is located on the bottom of each page, in front of the page number. The numbering convention for the DS number is "DSXXXXA", where "XXXX" is the document number and "A" is the revision level of the document.

For the most up-to-date information on development tools, see the MPLAB® IDE online help. Select the Help menu, and then Topics to open a list of available online help files.

INTRODUCTION

This chapter contains general information that will be useful to know before using the MGC3030 Woodstar Development Kit. Items discussed in this chapter include:

- Document Layout
- Conventions Used in this Guide
- Warranty Registration
- Recommended Reading
- The Microchip Web Site
- Development Systems Customer Change Notification Service
- Customer Support
- Revision History

DOCUMENT LAYOUT

This document describes the installation and use of the MGC3030 Woodstar Development Kit. The document is organized as follows:

- **Chapter 1. "Overview"**
- **Chapter 2. "Getting Started"**
- **Chapter 3. "Woodstar Boards – Hardware Description"**
- **Chapter 4. "System Integration Using Woodstar"**
- **Chapter 5. "Troubleshooting"**
- **Appendix A. "Schematics"**
- **Appendix B. "Sensitivity Profile and Capacitances"**
- **Appendix C. "Driver Installation Manual"**
- **Appendix D. "Glossary"**

MGC3030 Woodstar Development Kit User's Guide

CONVENTIONS USED IN THIS GUIDE

This manual uses the following documentation conventions:

DOCUMENTATION CONVENTIONS

Description	Represents	Examples
Arial font:		
Italic characters	Referenced books	<i>MPLAB[®] IDE User's Guide</i>
	Emphasized text	...is the <i>only</i> compiler...
Initial caps	A window	the Output window
	A dialog	the Settings dialog
	A menu selection	select Enable Programmer
Quotes	A field name in a window or dialog	"Save project before build"
Underlined, italic text with right angle bracket	A menu path	<u><i>File>Save</i></u>
Bold characters	A dialog button	Click OK
	A tab	Click the Power tab
N'Rnnnn	A number in verilog format, where N is the total number of digits, R is the radix and n is a digit.	4'b0010, 2'hF1
Text in angle brackets < >	A key on the keyboard	Press <Enter>, <F1>
Courier New font:		
Plain Courier New	Sample source code	#define START
	Filenames	autoexec.bat
	File paths	c:\mcc18\h
	Keywords	_asm, _endasm, static
	Command-line options	-Opa+, -Opa-
	Bit values	0, 1
	Constants	0xFF, 'A'
Italic Courier New	A variable argument	<i>file.o</i> , where <i>file</i> can be any valid filename
Square brackets []	Optional arguments	mcc18 [options] <i>file</i> [options]
Curly brackets and pipe character: { }	Choice of mutually exclusive arguments; an OR selection	errorlevel {0 1}
Ellipses...	Replaces repeated text	var_name [, var_name...]
	Represents code supplied by user	void main (void) { ... }

WARRANTY REGISTRATION

Please complete the enclosed Warranty Registration Card and mail it promptly. Sending in the Warranty Registration Card entitles users to receive new product updates. Interim software releases are available at the Microchip web site.

RECOMMENDED READING

This user's guide describes how to use the MGC3030 Woodstar Development Kit. Other useful documents are listed below. The following Microchip documents are available and recommended as supplemental reference resources.

- “*GestIC[®] Design Guide*” (DS40001716). This document describes the MGC3030/MGC3130 system characteristic parameters and the design process. It enables the user to generate a good electrode design and to parameterize the full GestIC[®] system.
- “*MGC3030/3130 GestIC[®] Library Interface Description User's Guide*” (DS40001718). This document is the interface description of the MGC3030/MGC3130 GestIC Library. It outlines the function of the Library's message interface, and contains the complete message reference to control and operate the MGC3030/MGC3130 system.
- “*MGC3030/3130 3D Gesture Controller Data Sheet*” (DS40001667). Consult this document for information regarding the MGC3030/MGC3130 3D Tracking and Gesture Controller.
- “*Aurea Graphical User Interface User's Guide*” (DS40001681). This document describes how to use the Aurea Graphical User Interface.

MGC3030 Woodstar Development Kit User's Guide

THE MICROCHIP WEB SITE

Microchip provides online support via our web site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

DEVELOPMENT SYSTEMS CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com, click on Customer Change Notification and follow the registration instructions.

The Development Systems product group categories are:

- **Compilers** – The latest information on Microchip C compilers, assemblers, linkers and other language tools. These include all MPLAB[®] C compilers; all MPLAB assemblers (including MPASM[™] assembler); all MPLAB linkers (including MPLINK[™] object linker); and all MPLAB librarians (including MPLIB[™] object librarian).
- **Emulators** – The latest information on Microchip in-circuit emulators. This includes the MPLAB REAL ICE[™] and MPLAB ICE 2000 in-circuit emulators.
- **In-Circuit Debuggers** – The latest information on the Microchip in-circuit debuggers. This includes MPLAB ICD 3 in-circuit debuggers and PICKit[™] 3 debug express.
- **MPLAB[®] IDE** – The latest information on Microchip MPLAB IDE, the Windows[®] Integrated Development Environment for development systems tools. This list is focused on the MPLAB IDE, MPLAB IDE Project Manager, MPLAB Editor and MPLAB SIM simulator, as well as general editing and debugging features.
- **Programmers** – The latest information on Microchip programmers. These include production programmers such as MPLAB REAL ICE in-circuit emulator, MPLAB ICD 3 in-circuit debugger and MPLAB PM3 device programmers. Also included are nonproduction development programmers such as PICSTART[®] Plus and PICKit 2 and 3.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at:

<http://www.microchip.com/support>.

REVISION HISTORY

Revision A (November, 2014)

Initial release of the document.

Revision B (January, 2015)

Updated the Recommended Reading section; Other minor corrections.

MGC3030 Woodstar Development Kit User's Guide

NOTES:



MGC3030 WOODSTAR DEVELOPMENT KIT USER'S GUIDE

Chapter 1. Overview

1.1 INTRODUCTION

MGC3030 is a product based on Microchip's patented GestIC[®] technology. It is developed as a mixed-signal controller. MGC3030 has one transmit and five very sensitive receive channels that are capable of detecting changes of a transmitted electrical field (E-field) corresponding to capacitive changes in the femtofarad (1 fF = 10⁻¹⁵F) range.

In order to transmit and receive an electrical field, electrodes have to be connected to the transmitting and receiving channels of the MGC3030 controller. The spatial arrangement of the electrodes allows the chip to determine the center of gravity of the electric field distortion, and thus gesture recognition of a user's hand in the detection space.

1.2 WOODSTAR CONCEPT AND DELIVERABLES

The Woodstar Development Kit is designed to support an easy integration of Microchip's MGC3030 3D Gesture Controller into the customer's applications. It provides MGC3030 system setup, related hardware and software references:

- Aurea Software Package with the Aurea Graphical User Interface and GestIC Library
- MGC3030/3130 Software Development Kit (SDK)
- MGC3030/3130 PIC18 Host Reference code

With the help of these tools, the design-in process can be easily performed in five steps:

1. Feature Definition
2. Electrode Design
3. MGC3030 Parameterization
4. Host Application Programming
5. Verification

Tutorial videos for the design-in process can be found on www.microchip.com/video/mid/tutorials.

Woodstar hardware builds a complete MGC3030 reference system consisting of three individual PCBs:

- MGC3030 Unit
- I²C[™] to USB Bridge
- Reference Electrode with a 95x60 mm sensitive area

MGC3030 Woodstar Development Kit User's Guide

It can be plugged to a PC via a USB cable and used for evaluation of the MGC3030 chip and the GestIC technology. During the customer's design-in process the individual boards can be combined according to the customer's needs.

Three examples are given below:

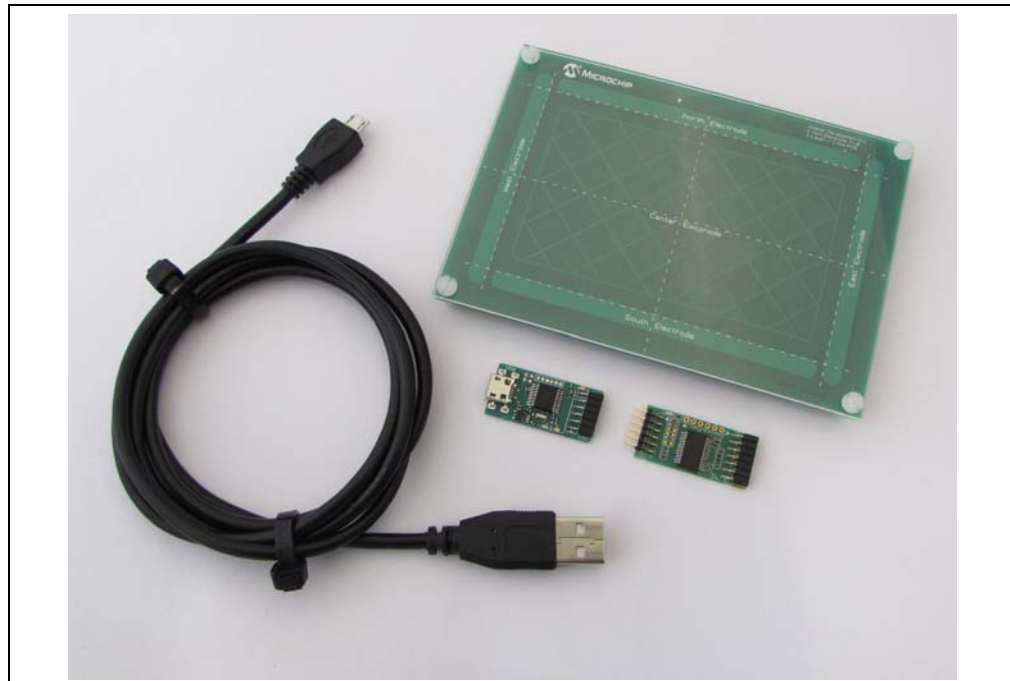
- Combine the MGC3030 unit and the I²C to USB bridge to evaluate customized electrodes
- Use the I²C to USB bridge to parameterize and debug the MGC3030 application circuitry in the customer's design
- Combine the MGC3030 unit and electrodes to develop gesture-driven applications for PC-based or embedded software environments

1.3 WOODSTAR DEVELOPMENT KIT PACKAGE CONTENT

The Woodstar Development Kit package content is listed below:

- MGC3030 Module
- I²C to USB Bridge Module
- Reference Electrode (95x60 mm sensitive area)
- USB Cable for PC Connection

FIGURE 1-1: WOODSTAR DEVELOPMENT KIT



1.4 GestIC[®] HARDWARE REFERENCES

The GestIC Hardware References package contains the PCB layouts (Gerber files) for the MGC3030/3130 development kits (Hillstar and Woodstar) and a collection of electrode reference designs fitting both kits. In addition, the package includes designs, parameter files and host code of various demonstrators which represent complete systems for embedded or PC-based applications.

New designs will be added to the package once they are available. The GestIC Hardware Reference package can be downloaded from Microchip's web site via www.microchip.com/gesticresources.

TABLE 1-1: PACKAGE CONTENT (BASED ON V1.0.6)

Module Name	Sensitive Area (mm)	Outline (mm)	PCB Layers	Fit to Hillstar	Fit to Woodstar	Parameter File	Host Code
MGC3130 Unit	—	—	2	√	—	—	—
MGC3030 Unit	—	—	2	—	√	—	—
I ² C™ to USB Bridge	—	—	2	√	√	—	(Note 1)
Reference Electrode 30x30 2-Layer	30x30	49x49	2	√	√	—	—
Reference Electrode 30x30 4-Layer	30x30	49x49	4	√	√	√	—
Reference Electrode 50x30 2-Layer	50x30	63x47	2	√	√	—	—
Reference Electrode 80x80 2-Layer	80x80	104x104	2	√	√	—	—
Reference Electrode 95x60 2-Layer	95x60	120x85	2	√	√	—	—
Reference Electrode 95x60 4-Layer	95x60	120x85	4	√	√	√	—
Reference Electrode 100x50 2-Layer	100x50	128x72	2	√	√	—	—
Reference Electrode 100x50 4-Layer	100x50	128x72	4	√	√	√	—
Reference Electrode 140x90 2-Layer	140x90	168x119	2	√	√	—	—
Reference Electrode Ring 95x60	95x60	120x85	2	√	√	√	—
Reference Electrode Ring 128x90	112x76	128x90	2	√	√	√	—
GestIC [®] Electrode Prototype Kit	85x85	100x110	N/A	—	—	—	—
MGC3130 Sensor Module 30x30	30x30	49x49	4	—	—	√	—
MGC3130 Sensor Module 95x60	95x60	120x85	4	—	—	√	—
MGC3130 Embedded Demo	42x75	60x150	2	—	—	√	√
MGC3130 Gesture Port Demo	D = 50	63.5x63.5	4	—	—	√	—

Note 1: Reference code for the PIC18F14K50 on the I²C to USB bridge can be found in the PIC18F14K50 Reference Code package on the Microchip web page.

MGC3030 Woodstar Development Kit User's Guide

1.5 AUREA SOFTWARE PACKAGE

The Aurea Software Package contains all relevant system software and documentation. The Woodstar Development Kit is supported by Aurea Software Package V1.2 onwards.

The package contains:

- Aurea PC Software
- GestIC Library (firmware) Binary File
- GestIC Parameterization Files
- Windows® CDC Driver
- Documentation

The latest Aurea Software Package can be downloaded from Microchip's web site via www.microchip.com/gesticresources.

Please find a collection of GestIC/Aurea tutorial videos at www.microchip.com/videohmidtutorials.

1.6 MGC3030/3130 SOFTWARE DEVELOPMENT KIT (SDK)

The MGC3030/3130 Software Development Kit (SDK) supports the integration of MGC3030 into a software environment. Thus, it includes a C reference code for GestIC API, a precompiled library for Windows operating systems, and a demo application using the GestIC API interface.

Woodstar Development Kit is supported by MGC3030/3130 SDK V1.1 onwards.

The latest SDK can be downloaded from Microchip's web site via www.microchip.com/gesticresources.

Chapter 2. Getting Started

The Woodstar Development Kit can be used as a stand-alone GestIC system and evaluated in conjunction with the Aurea PC software. This section describes how to get started.

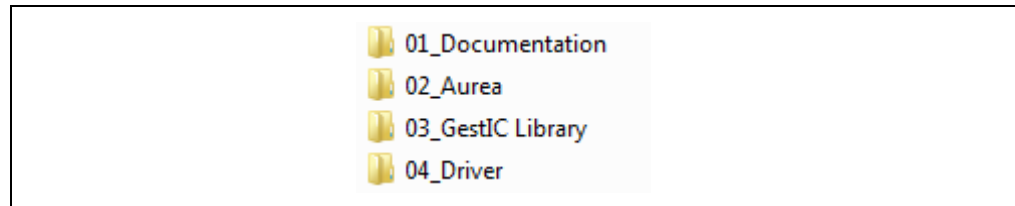
2.1 PREREQUISITES

The following prerequisites have to be fulfilled:

- PC with Windows 7 or Windows 8 operating systems, USB port and minimum screen resolution of 1024x768
- Woodstar Development Kit (MGC3030 unit, I²C to USB bridge, 95x60 mm frame electrode)
- Aurea Software Package V1.2 onwards

The Aurea Software Package is available as .zip file. Unzip the file, run `setup.exe` and install the package to the PC. The folder structure is as shown in [Figure 2-1](#).

FIGURE 2-1: FOLDER STRUCTURE



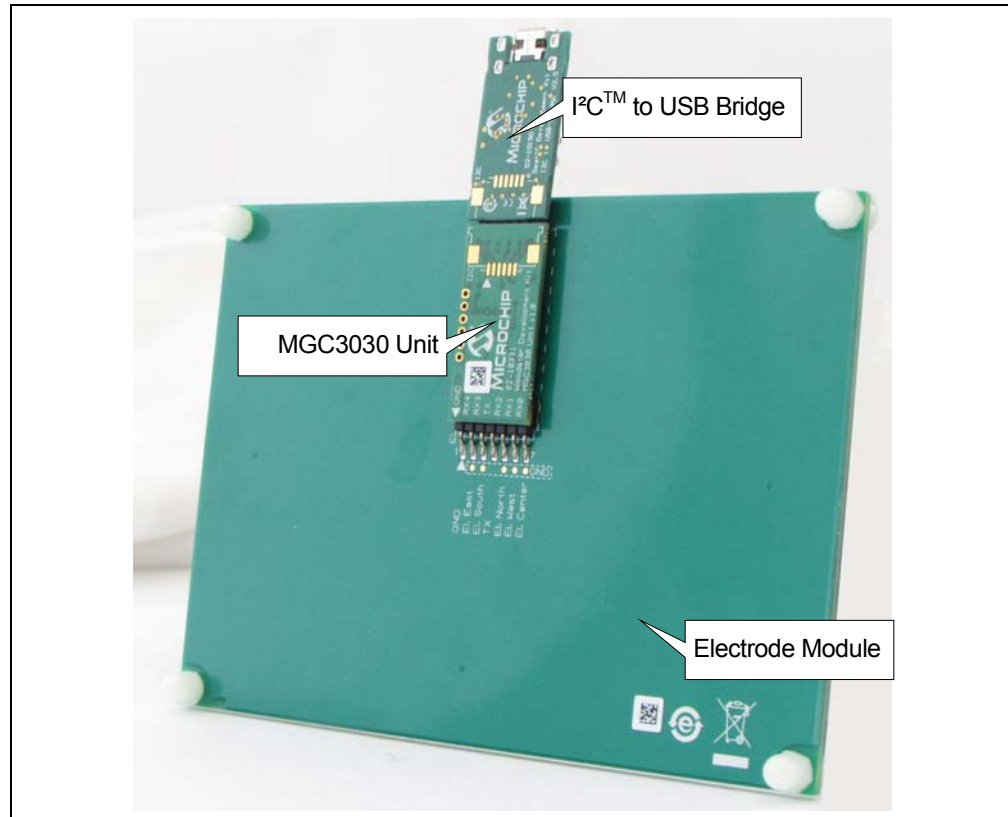
2.2 STEP 1: DEVELOPMENT KIT ASSEMBLY

Connect the electrodes, the MGC3030 unit and the I²C to USB bridge as shown in [Figure 2-2](#).

Note: Make sure the MGC3030 unit and the I²C to USB bridge are already connected before plugging in the USB connection.

MGC3030 Woodstar Development Kit User's Guide

FIGURE 2-2: WOODSTAR DEVELOPMENT KIT ASSEMBLY



2.3 STEP 2: CONNECTING THE WOODSTAR DEVELOPMENT KIT TO THE PC

Use the supplied USB cable to connect the Woodstar Development Kit to your PC. The power LEDs on both the I²C to USB bridge and the MGC3030 unit will illuminate. Furthermore, LED 1 on the I²C to USB bridge will flash very fast (~10 Hz). If LED 1 is flashing slow (~1 Hz), the Windows CDC driver is already installed on your PC. Please skip the next step and go to [Section 2.5 “Step 4: Starting Aurea GUI”](#).

2.4 STEP 3: INSTALLING WINDOWS[®] CDC DRIVER

The Windows CDC driver can be found in the Aurea Software Package in folder 04_Driver.

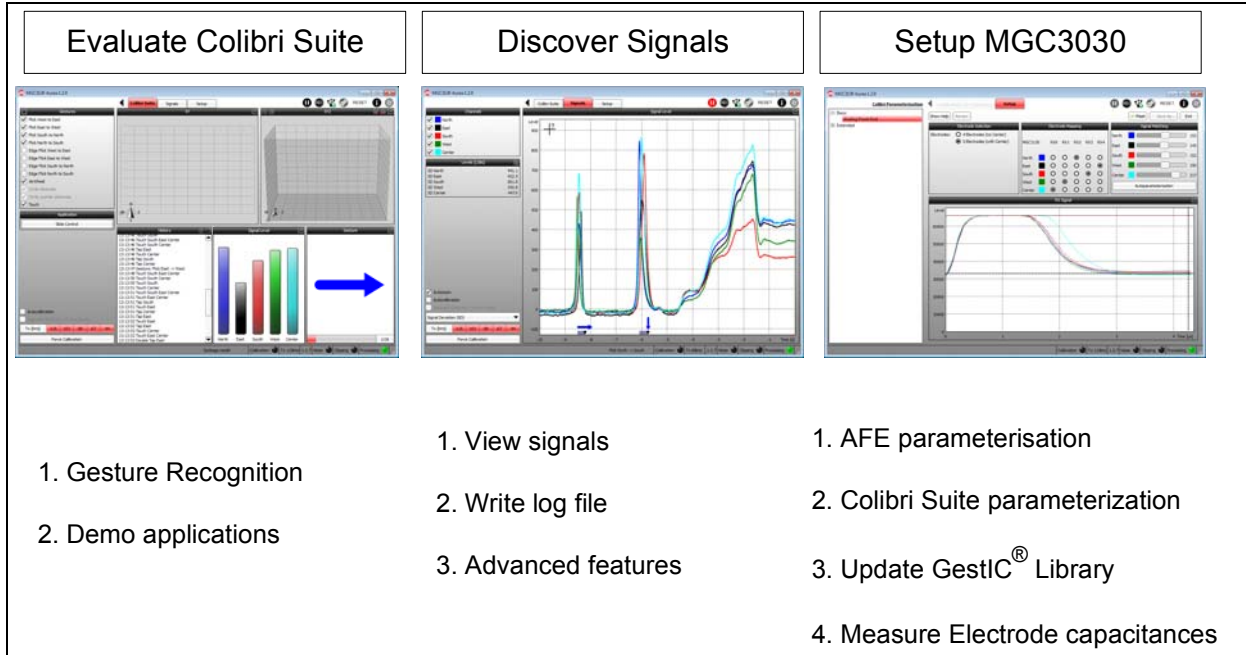
When the Woodstar Development Kit is connected to the PC for the first time, Windows requests the appropriate device driver and guides the user through the installation process. Alternatively, the driver can be installed manually, for example, by using the device manager. An example for Windows 7 is given in [Appendix C. “Driver Installation Manual”](#).

2.5 STEP 4: STARTING AUREA GUI

Aurea Graphical User Interface, shown in [Figure 2-3](#), is included in the Aurea Software Package in folder 02_Aurea.

Open `Aurea.exe`. Aurea automatically detects the connected device and is ready for use.

FIGURE 2-3: AUREA GRAPHICAL USER INTERFACE



MGC3030 Woodstar Development Kit User's Guide

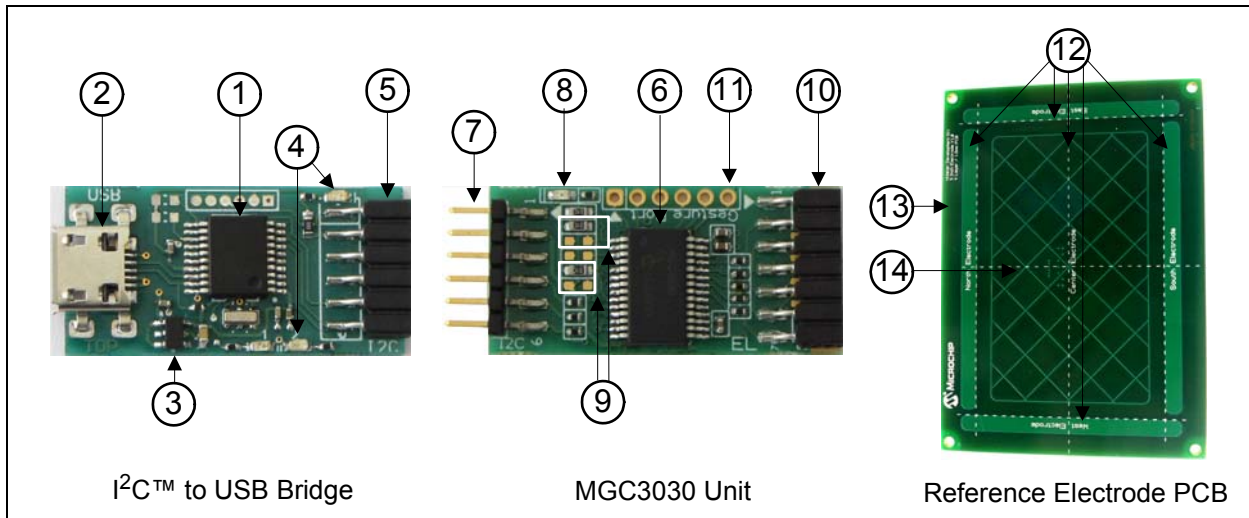
NOTES:

Chapter 3. Woodstar Boards – Hardware Description

3.1 OVERVIEW

The Woodstar key components are listed below and highlighted in [Figure 3-1](#).

FIGURE 3-1: WOODSTAR DEVELOPMENT KIT OVERVIEW



3.1.1 I²C™ to USB Bridge

1. PIC18F14K50 USB microcontroller
2. USB micro-B connector
3. MCP1801T LDO voltage regulator (converts 5V USB to 3.3V board supply)
4. Status LEDs (power, communication status)
5. Data interface: 6-pin socket for data communication and power supply

3.1.2 MGC3030 Unit

6. MGC3030 3D Gesture Controller
7. Data interface: 6-pin header for data communication and power supply
8. Status LED (power)
9. Interface select
10. Electrode interface: 7-pin socket
11. Gesture Port Header

3.1.3 95x60 mm Reference Electrode PCB

12. Receive electrodes
13. Acrylic cover glass (120 x 85 x 2 mm)
14. Electrode interface: 7-pin header (mounted on backside)

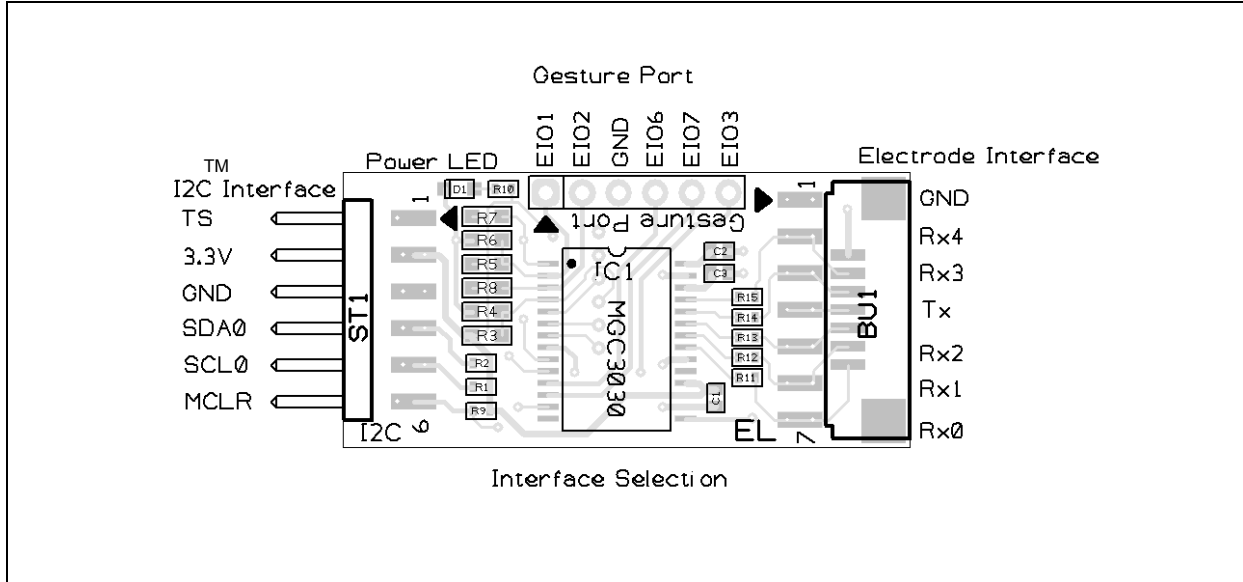
The Gerber data of all Woodstar Development Kit components are included in the GestIC Reference Design package and can be downloaded from Microchip's web site via www.microchip.com/gesticresources.

MGC3030 Woodstar Development Kit User's Guide

3.2 THE MGC3030 UNIT

The key element of the MGC3030 unit is Microchip's MGC3030 3D Gesture Controller. The layout print of the unit is shown in [Figure 3-2](#).

FIGURE 3-2: THE MGC3030 UNIT



The unit provides a 2 mm 7-pin board-to-board connector (socket) to connect the electrode. The interface includes the following signals: GND, Rx4, Rx3, Tx, Rx2, Rx1, and Rx0. Alternatively, the board-to-board connector can be replaced by a 1 mm Flexible Printed Circuitry (FPC) connector which is prepared as a design option. The five Rx channels of the MGC3030 (Rx0...Rx4) are connected to the receive electrodes via 10 kΩ resistors in order to suppress irradiated high-frequency signals (R11, R12, R13, R14, and R15). The MGC3030 signal generator is connected via the Tx signal to the transmit electrode. The access to the MGC3030 Gesture Port pins is provided by six pads at the side of the board (EIO1, EIO2, EIO6, EIO7, EIO3, and GND).

The data connection to the Woodstar I²C to USB bridge is done by a 2 mm 6-pin board-to-board connector (header). The interface includes the following signals: EIO0, 3.3V, GND, SDA0, SCL0, and MCLR. Alternatively, it is possible to use a 1 mm FPC connector which can be assembled to the bottom side.

The MGC3030 unit acts as an I²C slave device. Table 3-1 shows the configuration of the MGC3030 interface selection pins (IS1, IS2), which can be pulled to V_{DD} or to GND via resistors (R3, R4, R5, and R6) to select the I²C slave address. The I²C device address 0x42 is set as default.

TABLE 3-1: MGC3030 UNIT I²C™ INTERFACE SELECTION

MGC3030 Interface Selection Pins		Mode (Address)	Assembly Option			
IS2	IS1		R3	R4	R5	R6
0	0	I ² C™ Slave Address = 0x42 (default)	n.p.	10 kΩ	n.p.	10 kΩ
1	0	I ² C™ Slave Address = 0x43	10 kΩ	n.p.	n.p.	10 kΩ

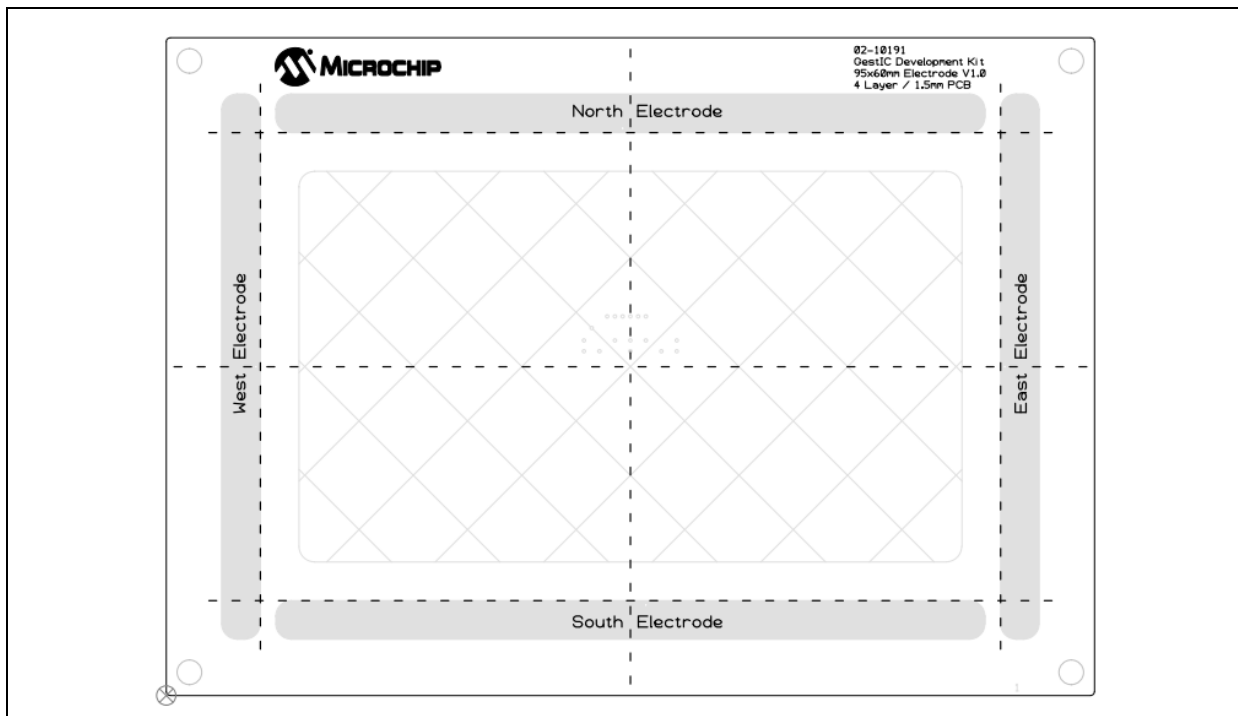
For schematics, layout and bill of material of the MGC3030 unit, please refer to [Appendix A. "Schematics"](#).

Woodstar Boards – Hardware Description

3.3 95x60 mm REFERENCE ELECTRODE

The 95x60 mm reference electrode provided with the Woodstar Development Kit consists of one Tx and a set of five Rx electrodes (north, east, south, west, center), which are placed in two different layers. An additional ground layer is placed underneath the Tx electrode to shield the electrode's back from external influences.

FIGURE 3-3: ELECTRODE LAYOUT



The PCB is connected to the MGC3030 unit by the 2 mm 7-pin board-to-board connector. The interface includes the following signals: GND, Rx4, Rx3, Tx, Rx2, Rx1, and Rx0.

The dimension of the board is 120 x 85 mm; the sensitive area is 95 x 60 mm.

The five Rx electrodes include four frame electrodes and one center electrode, as shown in [Figure 3-3](#). The frame electrodes are named according to their cardinal directions: North, East, South and West. The dimensions of the four Rx frame electrodes define the maximum sensing area. The center electrode is structured (cross-hatched) to get a similar input signal level as the four frame electrodes.

The Tx electrode spans over the complete area underneath the Rx electrodes. It is cross-hatched to reduce the capacitance between Rx and Tx (C_{RxTx}). The Tx area underneath the center electrode covers 50% of the copper plane, the area around the center electrode covers only 20%.

The Rx feeding lines are embedded into the Tx electrode in the third layer (refer to [Figure 3-4](#) and [Figure 3-5](#)). This supports shielding of the feeding lines. Dimensions are given in [Table 3-2](#).

MGC3030 Woodstar Development Kit User's Guide

FIGURE 3-4: ELECTRODE LAYOUT

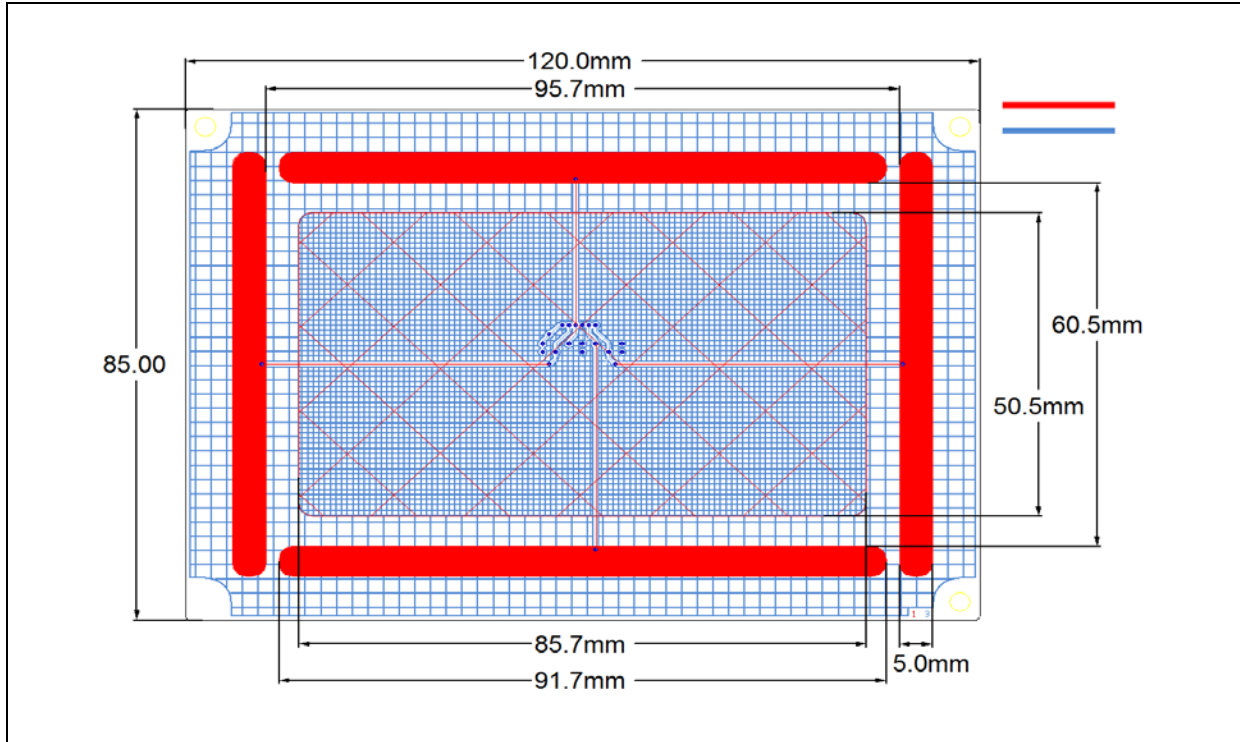


TABLE 3-2: WOODSTAR ELECTRODE DIMENSIONS

Part	Length	Width	Design
Horizontal Electrodes (Rx)	91.7 mm	5 mm	Solid
Vertical Electrodes (Rx)	70.5 mm	5 mm	Solid
Center Electrode (Rx)	85.7 mm	50.5 mm	3% cross-hatched
Tx Electrode (refer to Figure 3-4)	120 mm	85 mm	
Part I (under center electrode)	85.7 mm	50.5 mm	50% cross-hatched
Part II (outside Part I)	120 mm	85 mm	20% cross-hatched
Ground Area	120 mm	85 mm	Solid

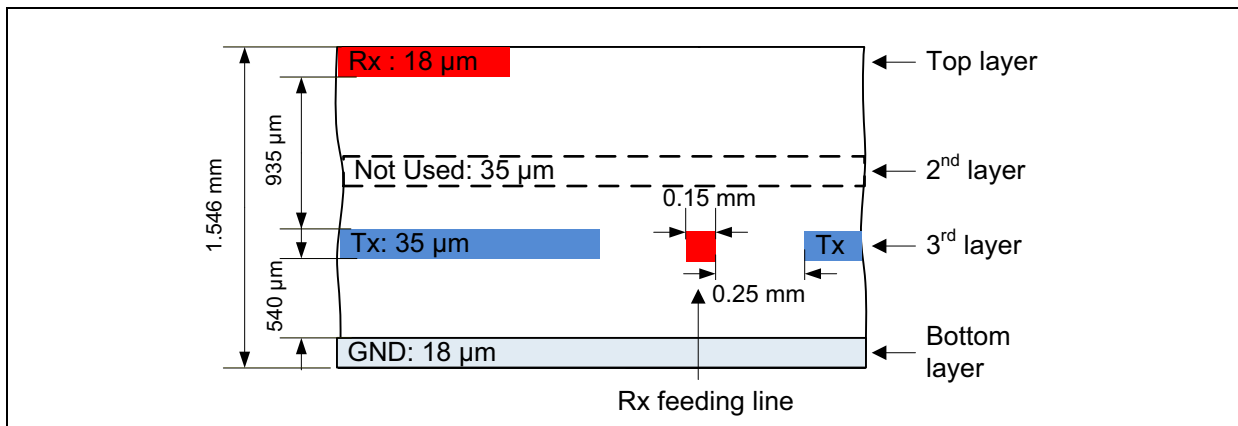
The electrode PCB is based on a 4-layer PCB design using FR4 material. Three functional layers are used:

- Layer 1 (Top): Rx electrodes
- Layer 3: Tx electrode and Rx feeding lines
- Layer 4 (Bottom): Ground

Layer 2 is not used.

Woodstar Boards – Hardware Description

FIGURE 3-5: PCB LAYER STACK



In a target system design the GND layer is not required. It is added for the Woodstar sensing electrode as a shielding layer and shall simulate the presence of static components which are placed in a target device underneath the sensing electrodes.

Note: Please refer to the “*GestIC® Design Guide*” for the electrodes equivalent circuitry, capacitances (C_{RxTx} , C_{RxG} , T_{RxG}) and their typical values.

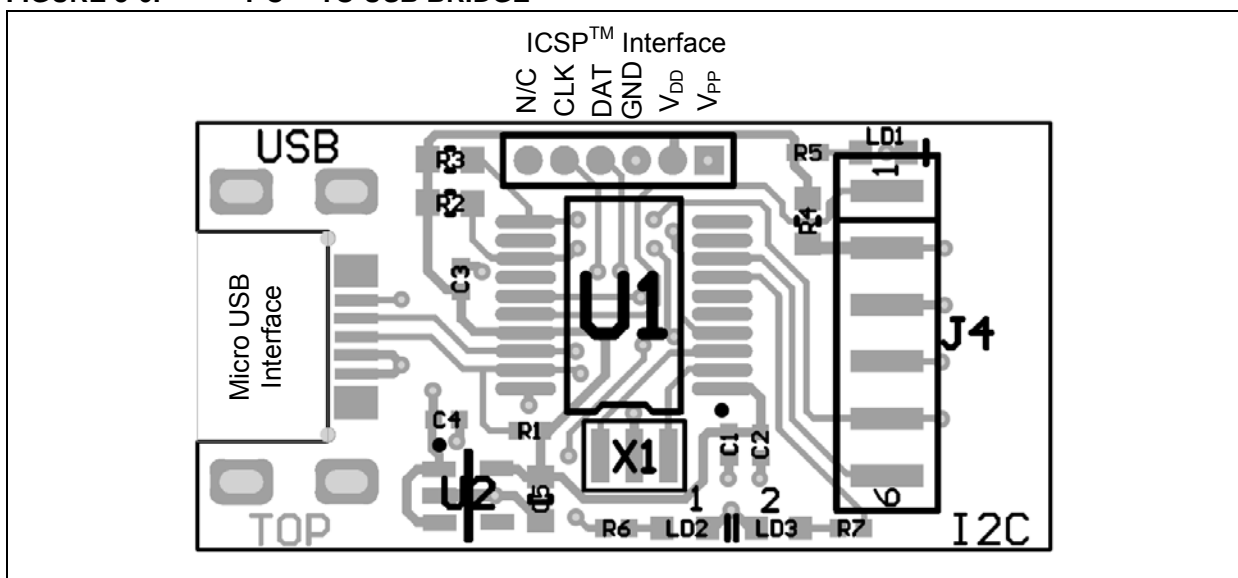
3.4 I²C TO USB BRIDGE

Connecting the MGC3030 unit to a PC requires an I²C to USB bridge. The GestIC bridge works as a composite device class (CDC). It controls the USB transfer towards the host PC and handles the I²C communication with the MGC3030 unit. Moreover, it provides 3.3V power supply and the MCLR signal to the MGC3030 unit.

The bridge function is handled by Microchip’s PIC18F14K50 USB microcontroller.

The board is equipped with a micro-USB connector (Type B) and a 2 mm 6-pin female board-to-board connector for the I²C interface. The interface to the MGC3030 unit includes the following signals: EIO0, 3.3V, GND, SDA0, SCL0, and MCLR. Please refer to [Figure 3-6](#).

FIGURE 3-6: I²C™ TO USB BRIDGE



MGC3030 Woodstar Development Kit User's Guide

The I²C to USB bridge is powered via the USB port. Microchip's Low Dropout (LDO) Voltage Regulator MCP1801 is used to transform the 5V USB power to 3.3V required for the PIC18F14K50. By default, 3.3V are also routed to the MGC3030 unit via the I²C interface. The 3.3V power supply towards the MGC3030 unit can be cut by removing the 0Ω resistor R7.

The LEDs indicate the following:

- Power – signals that the I²C to USB bridge is powered (3.3V)
- LED1 blinks fast (~10 Hz) – indicates that there is no USB connection established
- LED1 blinks slow (~1 Hz) – indicates that the USB connection is established
- LED 2 is ON when there is data on the I²C bus
- LED 2 is OFF when there is no data on the I²C bus

The communication between bridge and the MGC3030 unit is accomplished via a 2-wire I²C compatible serial port. Please refer to [Figure 3-7](#).

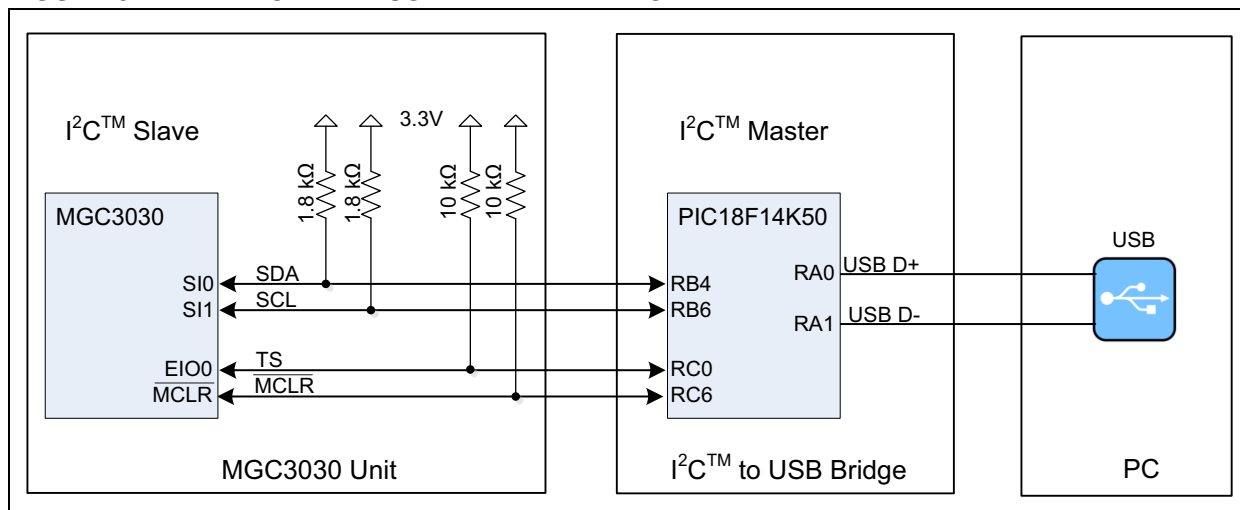
In addition, the Woodstar Development Kit integrates an open-drain transfer status line (TS) and the MGC3030 MCLR signal, according to the MGC3030 reference circuitry. TS is connected to the RC0 pin of the PIC18F14K50 and MCLR to RC6.

For a detailed description of the I²C interface refer to the "MGC3030/3130 3D Gesture Controller Data Sheet" (DS40001667).

The default I²C address of the bridge is set to 0x42 but it can also be switched to 0x43 by changing the firmware running on the PIC18F14K50.

Note: To update the PIC18F14K50 firmware, please refer to the MGC3030/3130 PIC18F14K50 Host Reference Code, available on Microchip's web site via www.microchip.com/gesticresources.

FIGURE 3-7: I²C™ AND USB DATA INTERFACE



For schematics, layout and bill of material of the I²C to USB bridge, please refer to [Appendix A. "Schematics"](#).

Chapter 4. System Integration Using Woodstar

4.1 INTRODUCTION

The Woodstar Development Kit is designed to support an easy integration of Microchip's MGC3030 3D Gesture Controller into the customer's applications.

The three Woodstar PCBs can be plugged to a PC via a USB cable and used for evaluation of the MGC3030 chip and the GestIC technology.

During the customer's design-in process the individual boards can be combined according to the customer's needs.

Three examples are given below:

- Combine MGC3030 unit and I²C to USB bridge to evaluate customized electrodes
- Use I²C to USB bridge to parameterize and debug the MGC3030 application circuitry in the customer's design (in-circuit)
- Combine MGC3030 unit and electrodes to develop gesture-driven applications for PC-based or embedded software environments

For in-circuit parameterization and debugging it is mandatory to control the MGC3030 unit via Aurea Control Software. For that purpose, the customer's application should provide an appropriate hardware or software interface.

4.2 INTEGRATION EXAMPLES

The following figures show typical hardware circuits for the integration of MGC3030 into a customer's application.

[Figure 4-1](#) and [Figure 4-2](#) show the control via I²C and an external PC. The Woodstar I²C to USB bridge acts as an I²C master. The application processor I²C should be:

- Switched OFF – I²C lines configured as high Z (refer to [Figure 4-1](#))
- Switched to Slave or Listen mode
- Disconnected through an external switch (refer to [Figure 4-2](#))

As an alternative, it is also possible to establish a USB connection between the application processor and a PC without using an I²C to USB bridge. Please refer to [Figure 4-3](#).

MGC3030 Woodstar Development Kit User's Guide

FIGURE 4-1: MGC3030 PARAMETERIZATION CIRCUIT WITH INTERNAL SWITCH

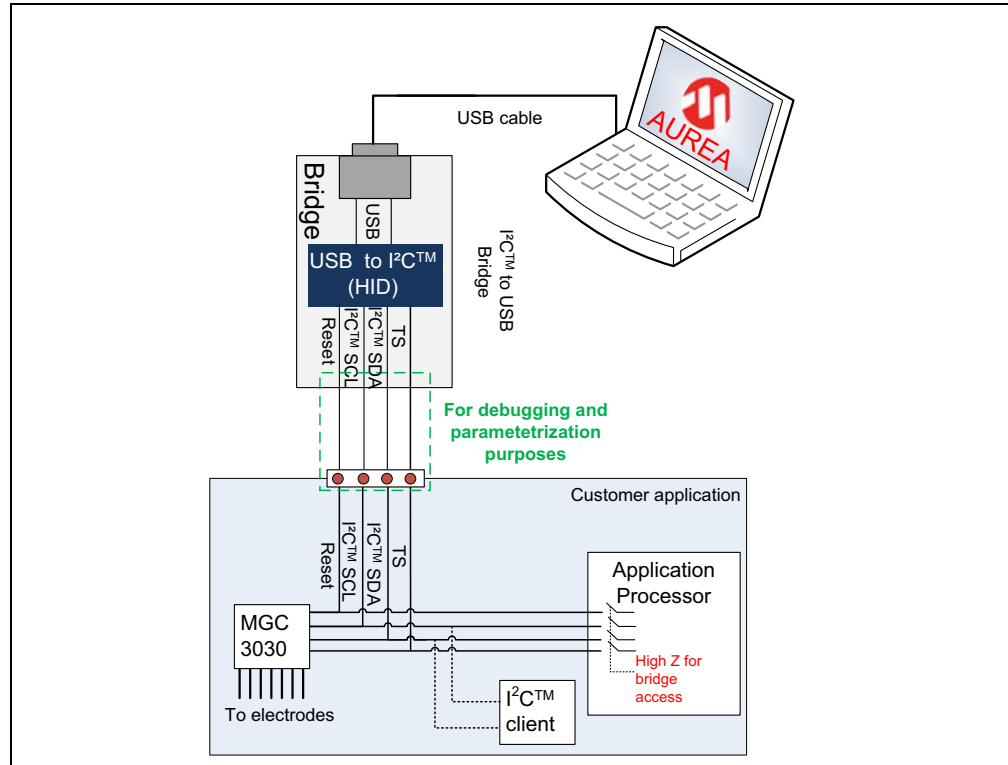
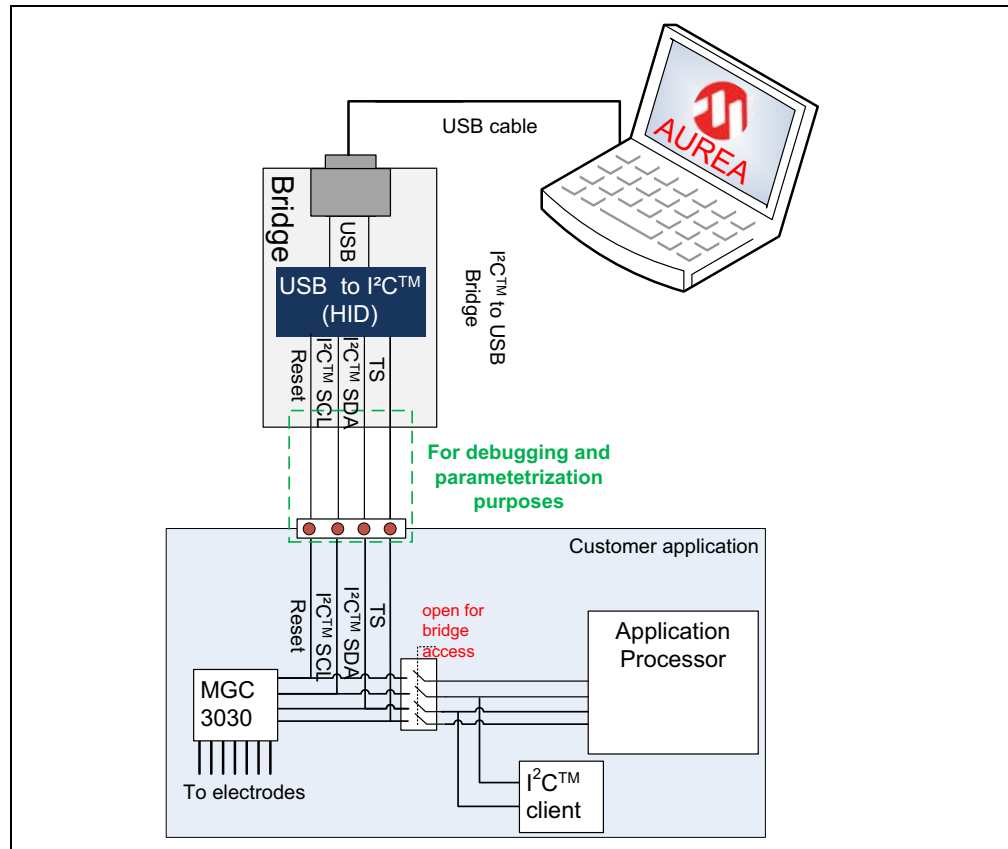


FIGURE 4-2: MGC3030 PARAMETERIZATION CIRCUIT WITH EXTERNAL SWITCH



System Integration Using Woodstar

FIGURE 4-3: MGC3030 PARAMETERIZATION CIRCUIT FOR USB-BASED APPLICATIONS

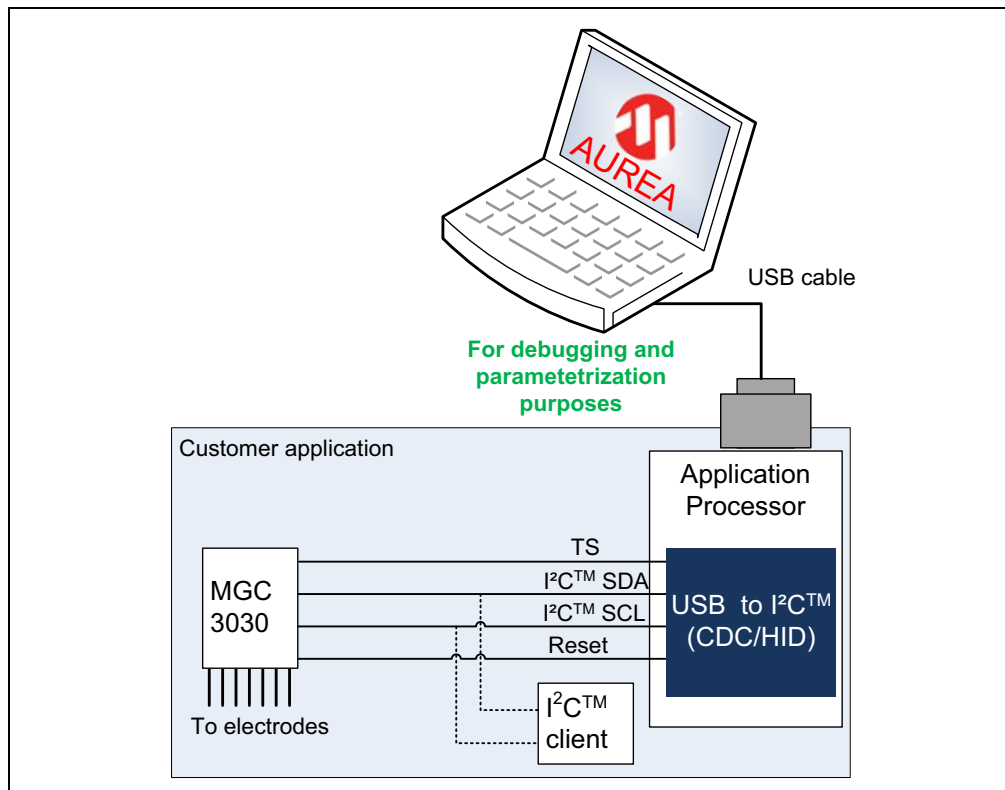


TABLE 4-1: MGC3030 PARAMETERIZATION CIRCUITS COMPARISON

Parameterization Circuit	Advantages	Drawbacks
With Internal Switch	Easy approach	Processor pins need to be switchable to high Z
	Low hardware efforts	No other clients can be controlled during Aurea access
With External Switch	Communication to other I ² C™ clients not interrupted	Additional hardware switch
USB-Based Applications	No hardware efforts	Additional software efforts
	Works if other I ² C™ clients connected to the bus	

MGC3030 Woodstar Development Kit User's Guide

NOTES:

Chapter 5. Troubleshooting

5.1 POWER LED DOES NOT ILLUMINATE

If the power LED does not illuminate, it is likely that the board is not powered.

Possible solutions:

- Check the board is connected to your PC's USB port.
- Change the USB cable or use a different USB port on your PC.
- Check if the PC is switched on.

5.2 LED 1 BLINKS FAST

When LED 1 blinks fast (~10 Hz), the USB connection is not established towards the PC.

Possible solutions:

- Make sure the Windows CDC driver is installed (refer to [Appendix C. "Driver Installation Manual"](#)).
- Make sure the MGC3030 unit and the I²C to USB bridge are already connected before plugging in the USB connection (refer to [Section 2.2 "Step 1: Development Kit Assembly"](#)).
- Reconnect the board by unplugging the USB connection and plugging it in again.

5.3 SIGNAL STREAMING STOPS

Signal stream in Aurea GUI stops when there is no approach towards the sensing area. This behavior is intended. When using the Aurea GUI, the Wake-up on Approach feature is automatically enabled.

Possible solutions:

Disable the Wake-up on Approach feature in the Real-Time Control bar of Aurea by unchecking the Approach Detection/Power Saving check box for continuous signal streaming.

5.4 ELECTRODE SIGNALS ARE ZERO

Signal matching parameters have been mismatched and accidentally stored into the Flash.

Possible solutions:

- Perform "Autoparameterization" in the AFE Parameterization of the **Aurea Setup** tab. Make sure there is no hand approach towards the electrodes during the autoparamterization process.
- Restore the default Signal Matching parameters by re-flashing the original MGC3030 GestIC Library file.

5.5 LED 1 AND 2 ON I²C TO USB BRIDGE ARE OFF

When LED 1 and LED 2 on the I²C to USB bridge are OFF but the power LED is ON, the PIC18F14K50 is in Bootloader Update mode and therefore not operating code. The PIC18F14K50 will start in Bootloader Update mode in case the MGC3030 unit is not connected to the I²C to USB bridge.

Possible solutions:

- Please disconnect the I²C to USB bridge from the USB. Connect the MGC3030 unit and the I²C to USB bridge first and then plug in the USB connection.

Appendix A. Schematics

A.1 INTRODUCTION

This appendix contains the MGC3030 Woodstar Development Kit schematic and bill of materials.

A.2 BILL OF MATERIALS

TABLE A-1: I²C™ TO USB BRIDGE BILL OF MATERIALS

Qty.	Description	Name
1	Connector, Micro USB 5-pin Type B, SMD	BU1
1	Connector, 2 mm socket 6-pin, SMD	BU2
1	Capacitor, 100 nF, 10%, X7R, SMD 0402	C1
3	Capacitor, 1 µF, 10%, X5R, 10 V, SMD 0402	C2, C3, C5
1	Capacitor, 10 µF, 20%, X5R, 6.3 V, SMD 0603	C4
3	LED, 571 nm, green clear, 0603 SMD	D1, D2, D3
1	IC, MCP1801T LDO, Voltage Regulator, 3.3V, 150 mA, 5-Pin SOT-23	IC1
1	IC, PIC18F14K50 USB Flash Microcontroller, 20-Pin SSOP	IC2
3	Resistor, 1 kΩ, 1%, 1/16W, SMD 0402	R3, R4, R6
1	Resistor, 150 kΩ, 1%, 1/16W, SMD 0402	R5
1	Resistor, 0 kΩ, 1%, 1/16W, SMD 0603	R7
1	Crystal, 12 MHz, 33 pF, SMD	XTAL1

TABLE A-2: I²C™ TO USB BRIDGE MOUNTING OPTION

Qty.	Description	Name
1	Connector, 1 mm FPC 6-pin, SMD	ST1

MGC3030 Woodstar Development Kit User's Guide

TABLE A-3: MGC3030 UNIT BILL OF MATERIALS

Qty.	Description	Name
1	Connector, 2mm socket 7pin, SMD	BU1
1	Connector, 2mm header 6pin, SMD	ST1
1	Capacitor, 100nF, 10%, X7R, SMD 0402	C1
2	Capacitor, 4.7 μ F, 20%, X5R, 6.3V, SMD 0402	C2, C3
1	LED, 571nm green clear, 0603 SMD	D1
1	IC, MGC3030 3D Gesture Controller, 28 Pin SSOP	IC1
2	Resistor, 1.8k Ω , 1%, 1/16W, SMD 0402	R1, R2
3	Resistor, 10k Ω , 1%, 1/16W, SMD 0603	R4, R6, R7
6	Resistor, 10k Ω , 1%, 1/16W, SMD 0402	R9, R11, R12, R13, R14, R15
1	Resistor, 1k Ω , 1%, 1/16W, SMD 0402	R10

TABLE A-4: MGC3030 UNIT MOUNTING OPTION

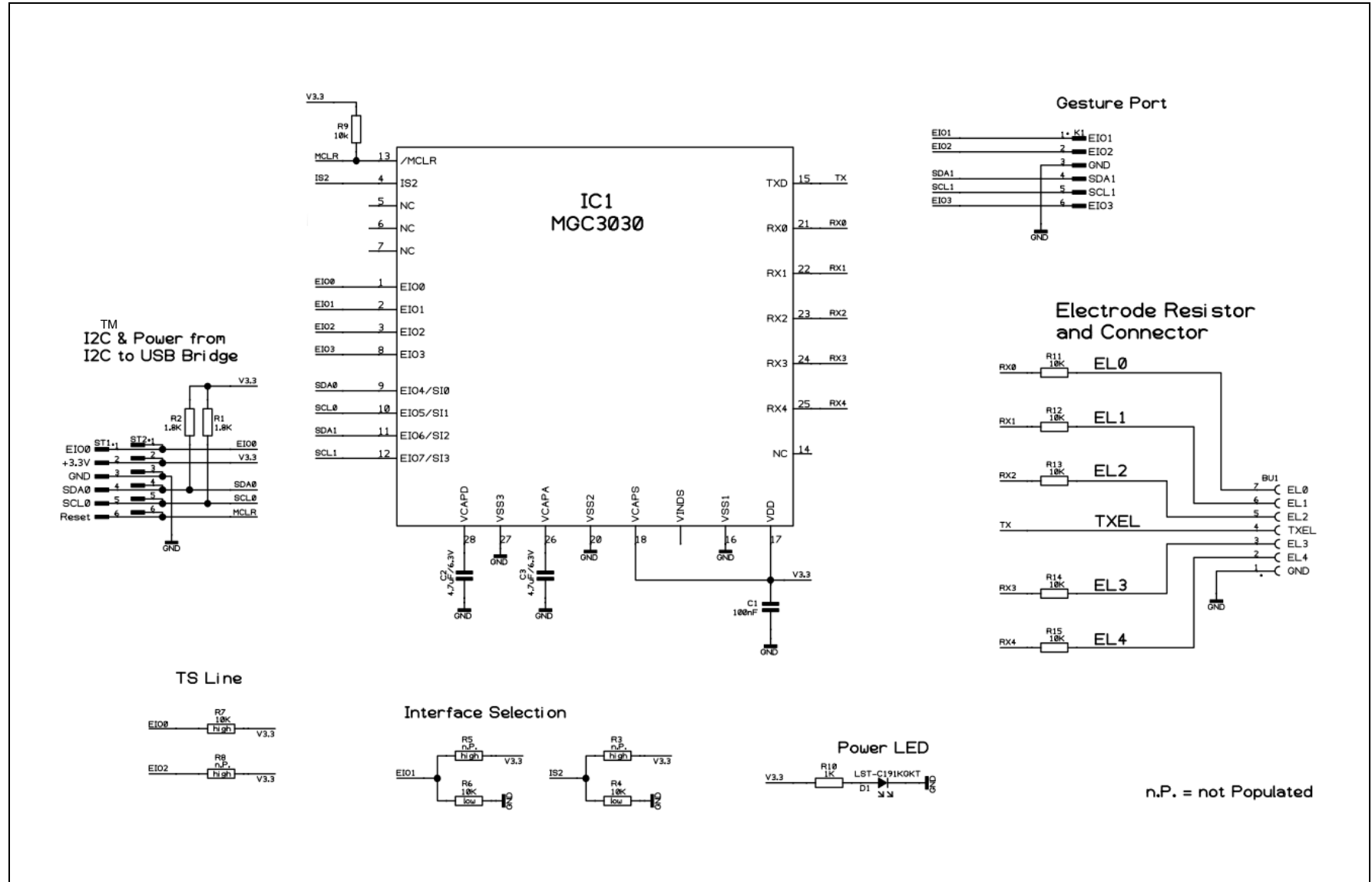
Qty.	Description	Name
1	Connector, 1 mm FPC 6-pin, SMD	ST3

TABLE A-5: REFERENCE ELECTRODE BILL OF MATERIALS

Qty.	Description	Name
1	Connector, 1 mm FPC 6-pin, SMD	ST2

A.3 BOARD SCHEMATICS AND LAYOUT

FIGURE A-1: MGC3030 UNIT SCHEMATIC



MGC3030 Woodstar Development Kit User's Guide

FIGURE A-2: ASSEMBLY OF MGC3030 UNIT

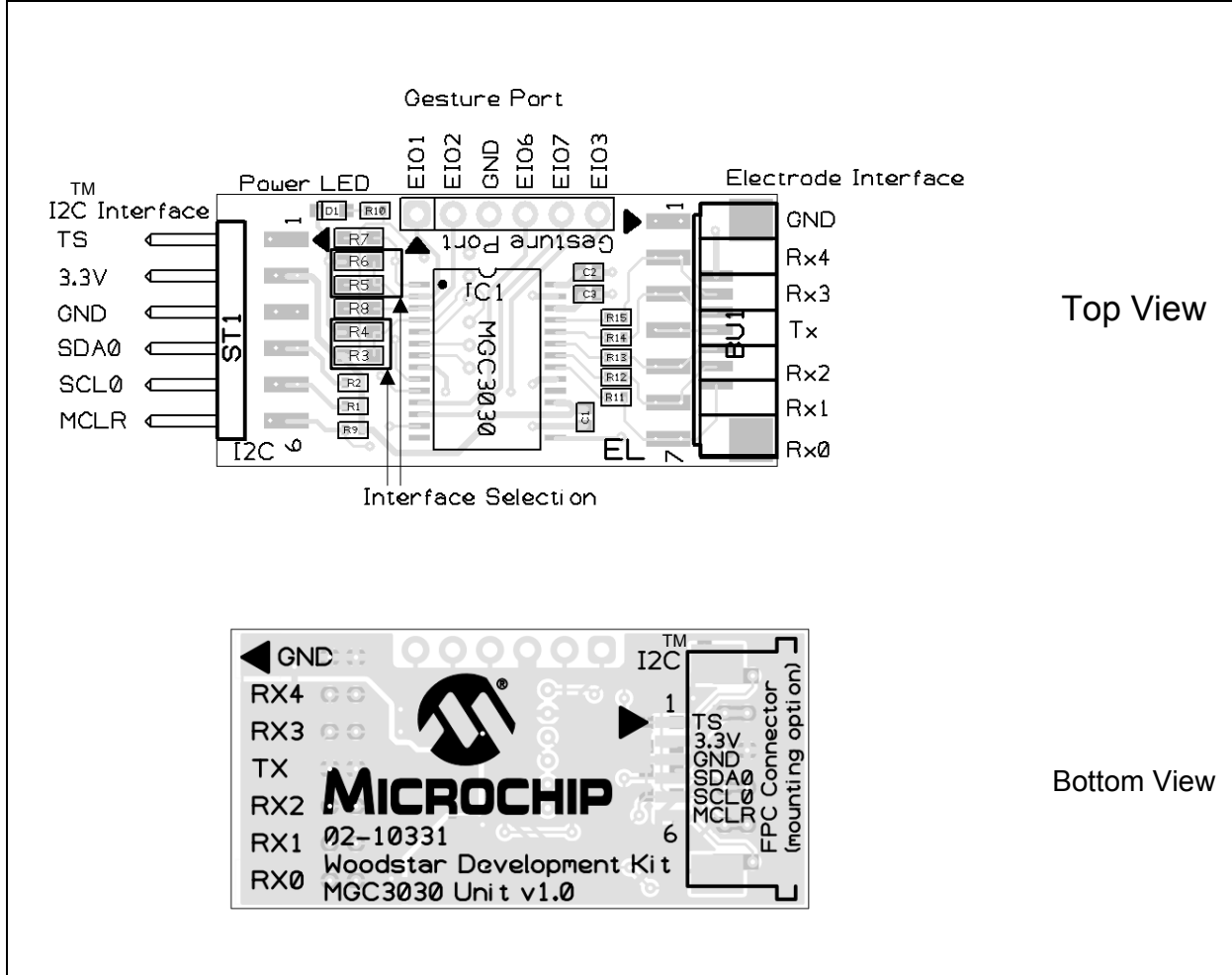
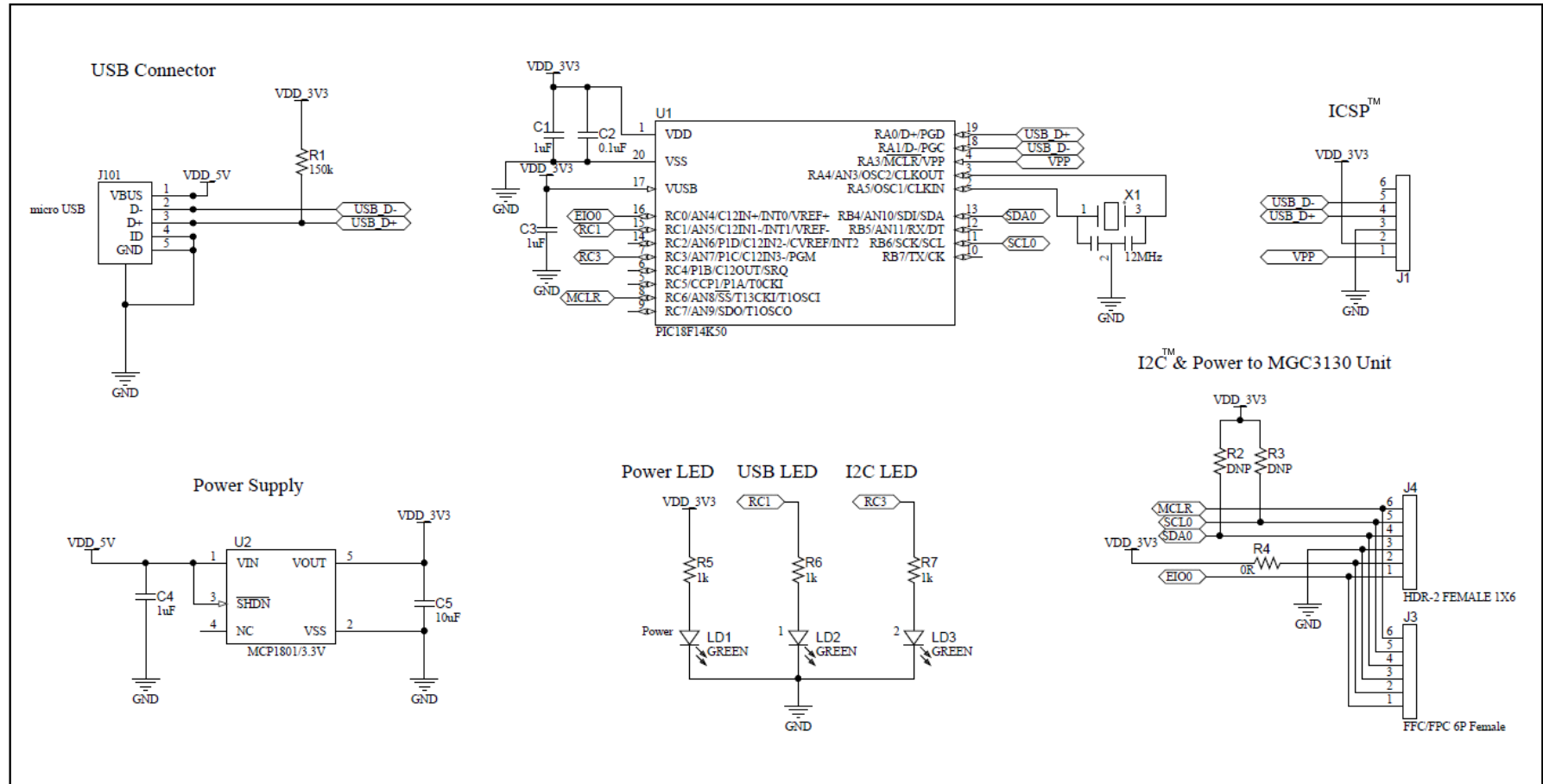
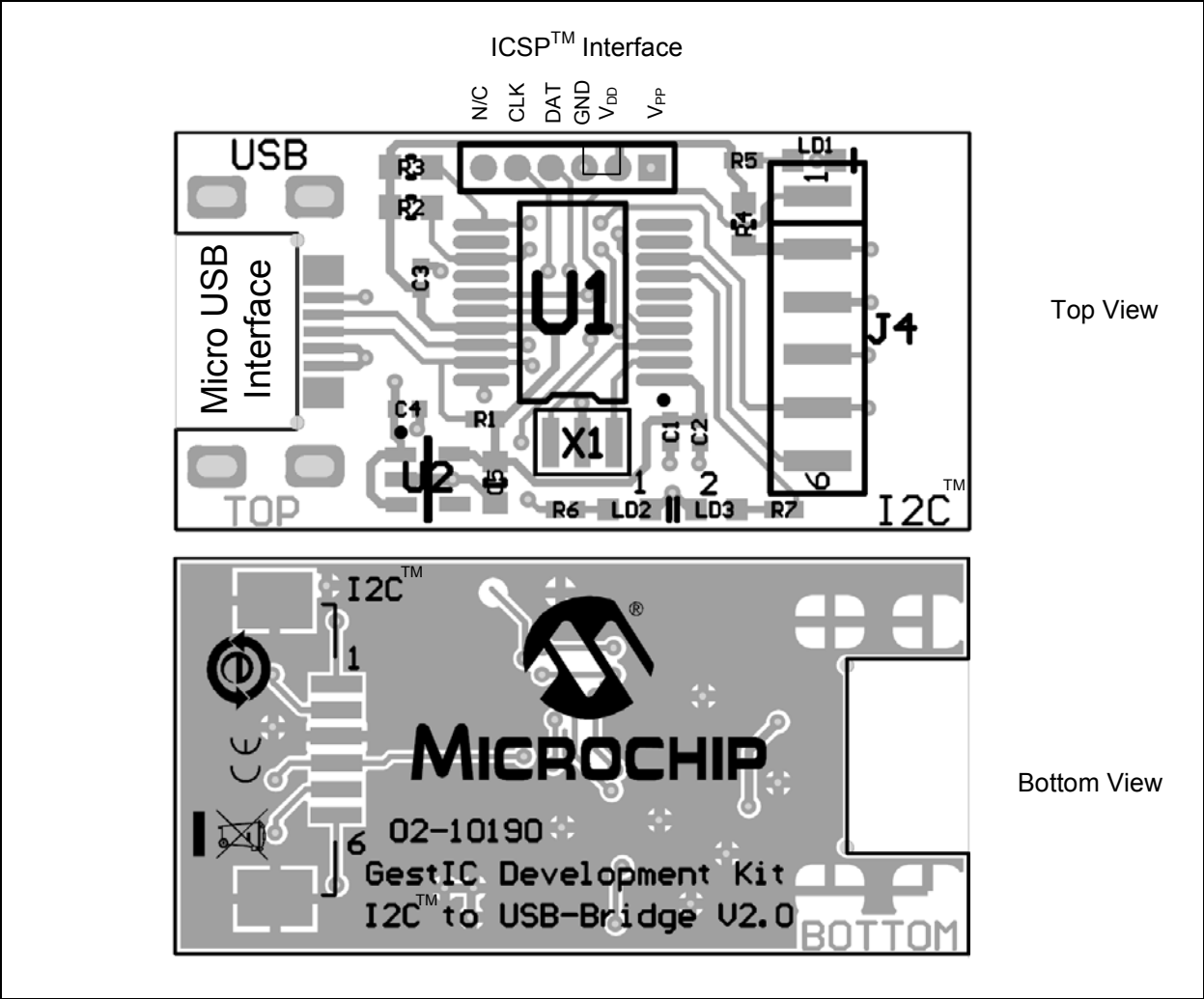


FIGURE A-3: I²C™ TO USB BRIDGE SCHEMATIC



MGC3030 Woodstar Development Kit User's Guide

FIGURE A-4: ASSEMBLY OF I²C™ TO USB BRIDGE



Appendix B. Sensitivity Profile and Capacitances

B.1 INTRODUCTION

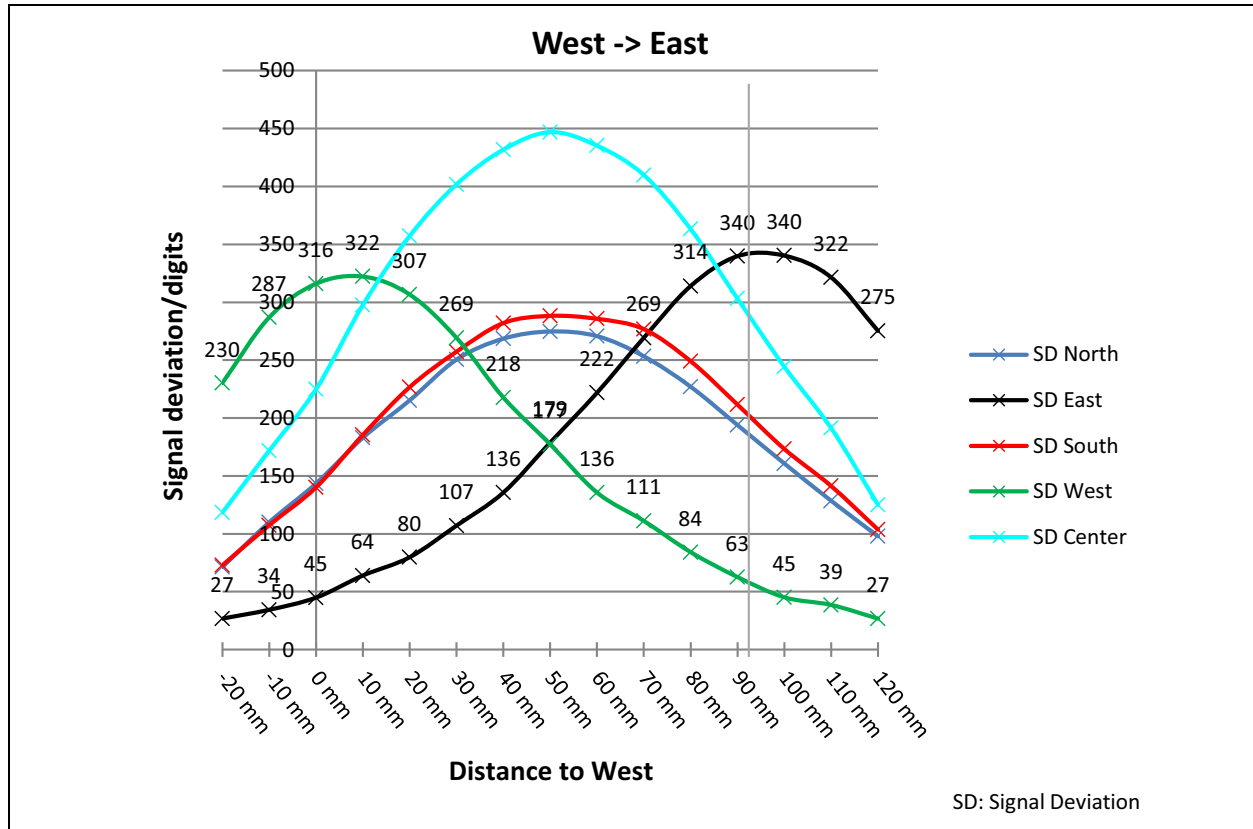
This appendix contains the sensitivity profile and the electrode capacitances of the Woodstar Development Kit hardware.

The measurement procedure of both the sensitivity profile and the electrode capacitances are outlined in “*GestIC® Design Guide*” (DS40001716).

B.2 SENSITIVITY PROFILES

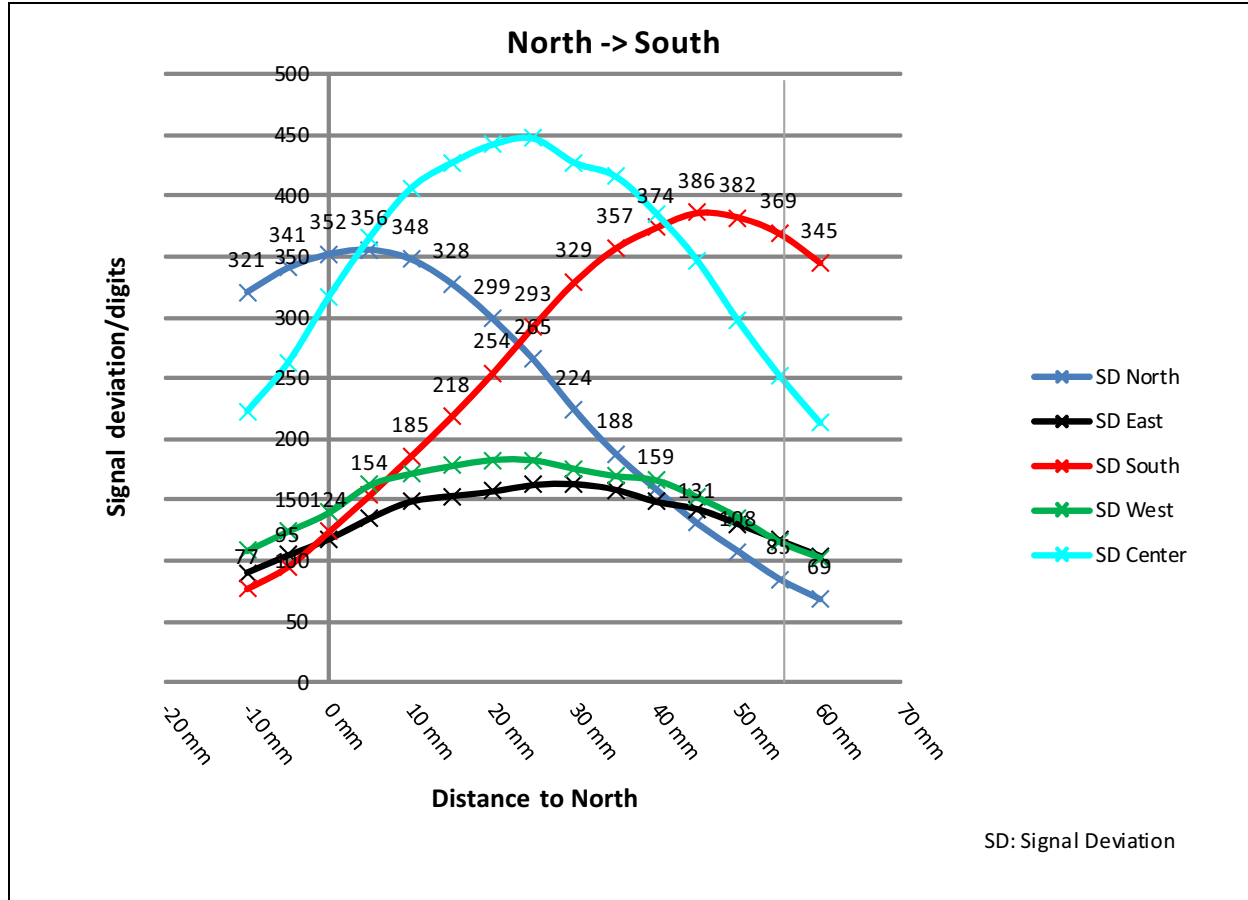
The sensitivity profiles were conducted using a 40x40x70 mm artificial hand at a constant height of 30 mm above the electrode's surface.

FIGURE B-1: SENSITIVITY PROFILE FROM WEST TO EAST



MGC3030 Woodstar Development Kit User's Guide

FIGURE B-2: SENSITIVITY PROFILE FROM NORTH TO SOUTH



B.3 ELECTRODE CAPACITIES

The capacitances between the Rx electrodes and GND (C_{RXG}) do not include the 5 pF input capacitance of the MGC3030 Rx input buffer (C_{Buf}).

TABLE B-1: GestIC® ELECTRODE CAPACITIES⁽¹⁾

Channel	C_{RXG}	C_{RXTX}
North	9 pF	20 pF
East	9 pF	18 pF
South	9 pF	20 pF
West	8 pF	18 pF
Center	7 pF	65 pF

Note 1: $C_{TXG} = 590$ pF

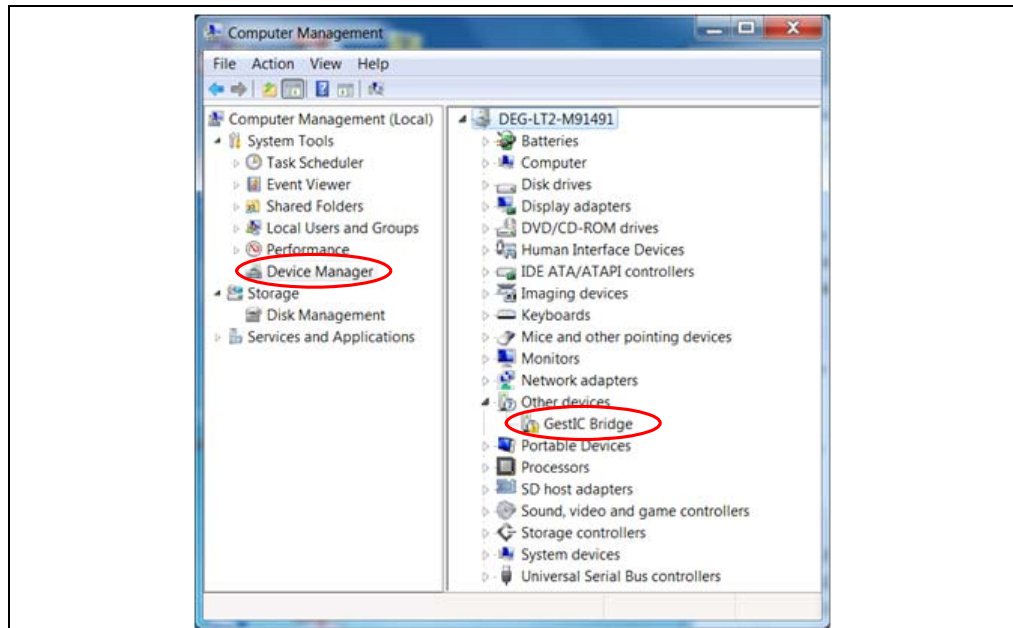
Appendix C. Driver Installation Manual

This section lists the steps to be taken in order to manually install the Windows CDC Driver on the PC.

C.1 OPEN DEVICE MANAGER

While the Woodstar Development Board is connected to the PC press **Start**, right-click on **Computers** and select **Manage**. This will bring up the Computer Management window shown in Figure C-1. On the left sidebar select **Device Manager**.

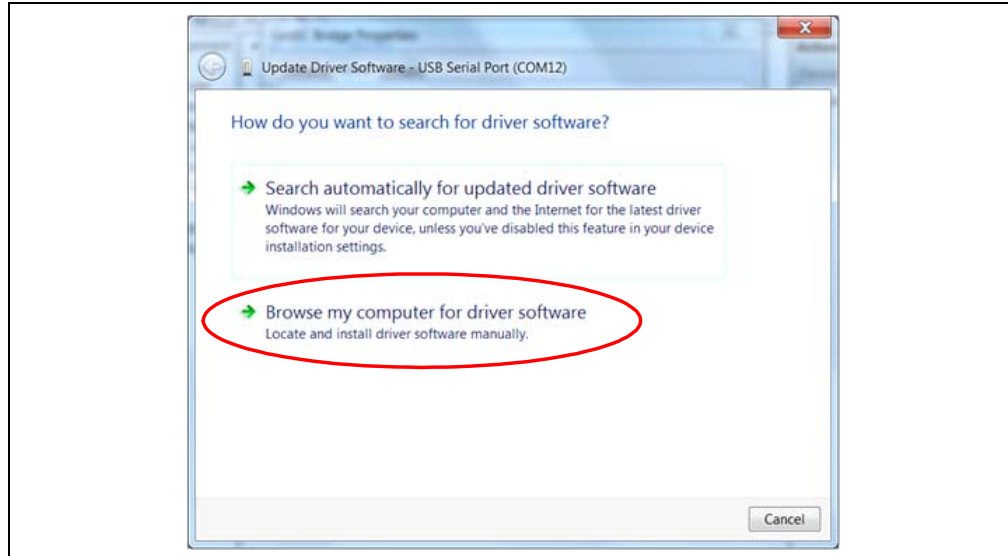
FIGURE C-1: COMPUTER MANAGEMENT



C.2 SELECT DEVICE

1. Right Click on **GestIC Bridge** and select **Update Driver Software**.
2. Select **Search Method**
3. The window shown in Figure C-2 will open. Choose **Browse my Computer** for driver software.

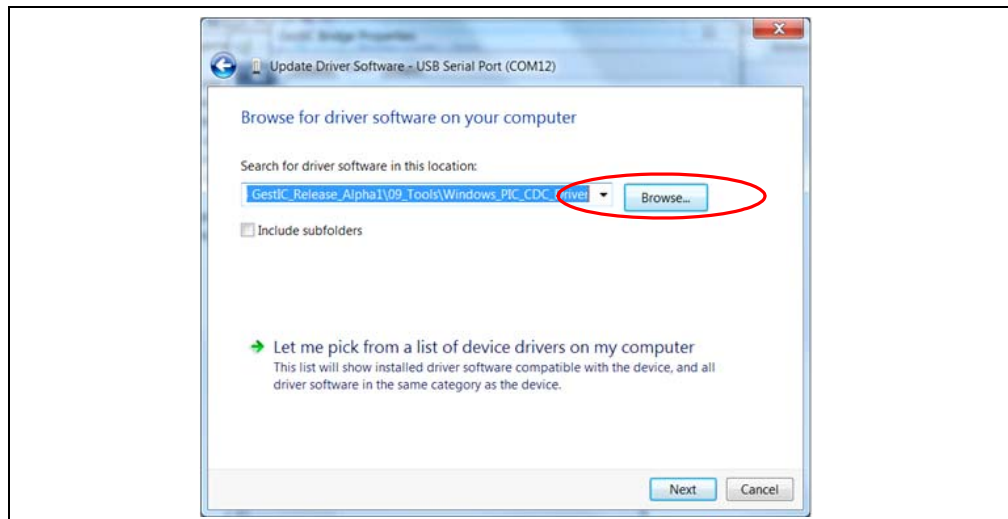
FIGURE C-2: Update Driver Software



C.3 LOCATE DRIVER

1. Click **Browse** and navigate to the driver files on your local drive (refer to Figure C-3).
2. Press **Next** and the driver will be installed.

FIGURE C-3: Browse for Driver Software



C.4 VERIFY COMMUNICATION

The driver is properly installed and the communication between the PC and the Woodstar Development Board is successfully established when LED 1 and LED 2 blink alternatively.

Appendix D. Glossary

TABLE D-1: GLOSSARY

Term	Definition
AFE	Analog Front End
Application Host	PC or embedded controller which controls the MGC3030
Aurea	MGC3030/3130 PC control software with graphical user interface
Colibri Suite	Embedded DSP suite within the GestIC [®] Library
Deep Sleep	MGC3030/3130 Power-Saving mode
E-field	Electrical field
Frame Electrodes	Rectangular set of four electrodes for E-field sensing
GestIC [®] Technology	Microchip's patented technology providing 3D free-space gesture recognition utilizing the principles of electrical near-field sensing
GestIC [®] Library	Includes the implementation of MGC3030/3130 features and is delivered as a binary file preprogrammed on the MGC3030
Gesture Recognition	Microchip's stochastic HMM classifier to automatically detect and classify hand movement patterns
Gesture Set	A set of provided hand movement patterns
HMM	Hidden Markov Model
MGC3130	Single-Zone 3D Gesture and Motion Tracking Controller
MGC3030	Single-Zone 3D Gesture Sensing Controller
Position Tracking	GestIC [®] technology feature
Self Wake-up	MGC3030/3130 Power-Saving mode
Sensing Area	Area enclosed by the four frame electrodes
Sensing Space	Space above sensing area
Signal Deviation	Term for the delta of the sensor signal on approach of the hand versus non-approach
SPU	Signal Processing Unit
Approach Detection	GestIC [®] technology feature: Power-Saving mode of the MGC3030/3130 with approach detection

MGC3030 Woodstar Development Kit User's Guide

NOTES:



MICROCHIP

Worldwide Sales and Service

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://www.microchip.com/support>
Web Address:
www.microchip.com

Atlanta
Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Austin, TX
Tel: 512-257-3370

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland
Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Novi, MI
Tel: 248-848-4000

Houston, TX
Tel: 281-894-5983

Indianapolis
Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

New York, NY
Tel: 631-435-6000

San Jose, CA
Tel: 408-735-9110

Canada - Toronto
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2943-5100
Fax: 852-2401-3431

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing
Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hangzhou
Tel: 86-571-8792-8115
Fax: 86-571-8792-8116

China - Hong Kong SAR
Tel: 852-2943-5100
Fax: 852-2401-3431

China - Nanjing
Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao
Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen
Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai
Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi
Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune
Tel: 91-20-3019-1500

Japan - Osaka
Tel: 81-6-6152-7160
Fax: 81-6-6152-9310

Japan - Tokyo
Tel: 81-3-6880-3770
Fax: 81-3-6880-3771

Korea - Daegu
Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur
Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang
Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila
Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung
Tel: 886-7-213-7830

Taiwan - Taipei
Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Dusseldorf
Tel: 49-2129-3766400

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Germany - Pforzheim
Tel: 49-7231-424750

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Italy - Venice
Tel: 39-049-7625286

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Poland - Warsaw
Tel: 48-22-3325737

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

Sweden - Stockholm
Tel: 46-8-5090-4654

UK - Wokingham
Tel: 44-118-921-5800
Fax: 44-118-921-5820

03/25/14

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Microchip:](#)

[DM160226](#)

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9